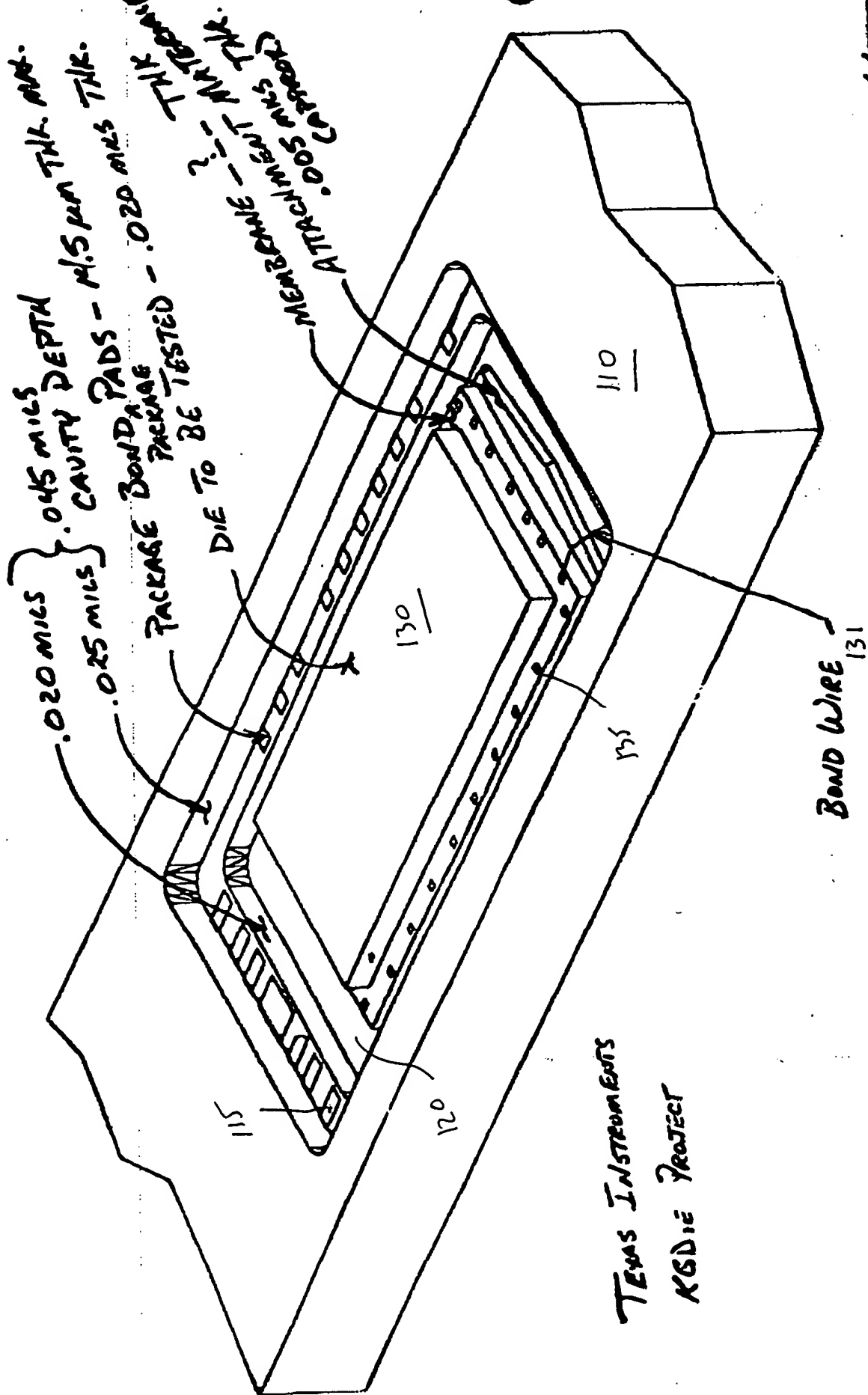


Figure 2 Flip Configuration of K6DIE Package, Exploded View

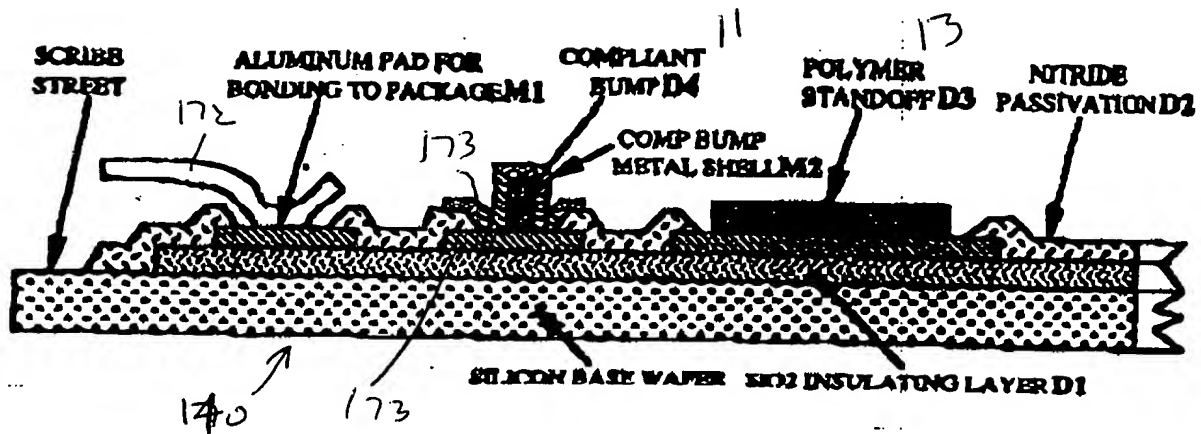


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Figure 3 Compliant bump with polymer standoff on KGD/IL silicon membrane, Cross Section.



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MILITARY PRODUCTS DIVISION

PRODUCTION BY USE OF EXISTING BURN-IN AND TEST TOOLING

- **MULTI BOND LAYER PACKAGE**
- **SINGLE ALIGNMENT PROCESS**
- **REUSABLE**
- **SAVE COST AS OF ORIGINAL CONFIGURATION**

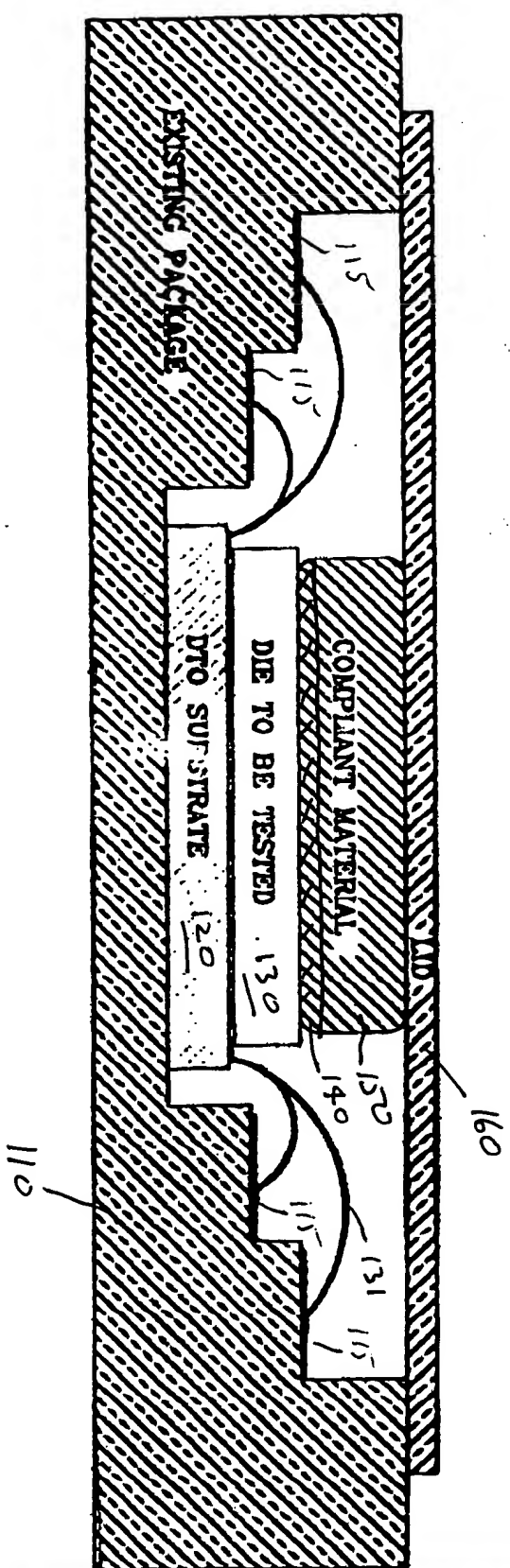


FIGURE 1: Generic KGD/IE Implementation, Exploded view

140. Interconnecting Medium (Inverted View)

171. Inner connection
172. Outer connection
173. Conductive Path

Fig. 1b

Fig. 1a

160. Package Lid
150. Upper Compliant Material
140. Interconnecting Medium
(oriented for assembly)
130. Semiconductor Die
135. Bond Pads
120. Lower Compliant Material

110. Standard IC Package
115. Package Terminals

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